



**IN THE CLAIMS:**

1. (Original) A film formation method comprising the steps of:  
forming a first film in a chamber by using a first gas;  
installing a substrate into the chamber after forming the first film; and  
forming a second film over a surface of the substrate by using the first film and  
a second gas.
2. (Original) A film formation method according to claim 1, wherein the  
second film is formed at a pressure of 20 Pa or less.
3. (Original) A film formation method according to claim 1, wherein the  
second film is formed over one selected from the group consisting of a glass substrate,  
a plastic substrate, and an organic resin film.
4. (Original) A film formation method according to claim 1, wherein the  
first film is formed by plasma CVD, and the second film is precipitated by sputtering.
5. (Original) A film formation method according to claim 1, wherein a  
semiconductor device is manufactured by using the second film as a protective film of  
a semiconductor element.
6. (Currently Amended) A film formation method according to claim [[1]]  
5, wherein the semiconductor element comprises at least one selected from the group  
consisting of a thin film transistor, an organic thin film transistor, a thin film diode, a  
photoelectric conversion element, and a resistor.
7. (Original) A film formation method comprising the steps of:  
forming a first film in a chamber by using a first gas;

installing a substrate into the chamber after forming the first film; and  
forming a silicon nitride film over a surface of the substrate by using the first film and a second gas.

8. (Original) A film formation method according to claim 7, wherein the first gas comprises a silicide gas and nitrogen.

9. (Original) A film formation method according to claim 7, wherein the second gas comprises at least one selected from the group consisting of helium (He), neon (Ne), argon (Ar), krypton (Kr), and xenon (Xe).

10. (Original) A film formation method according to claim 7, wherein the second film is formed at a pressure of 20 Pa or less.

11. (Original) A film formation method according to claim 7, wherein the second film is formed over one selected from the group consisting of a glass substrate, a plastic substrate, and an organic resin film.

12. (Original) A film formation method according to claim 7, wherein the first film is formed by plasma CVD, and the second film is precipitated by sputtering.

13. (Original) A film formation method according to claim 8, wherein the silicide gas comprises at least one selected from the group consisting of monosilane, disilane, and trisilane.

14. (Original) A film formation method according to claim 7, wherein a semiconductor device is manufactured by using the second film as a protective film of a semiconductor element.

15. (Currently Amended) A film formation method according to claim [[7]] 14, wherein the semiconductor element comprises at least one selected from the group consisting of a thin film transistor, an organic thin film transistor, a thin film diode, a photoelectric conversion element, and a resistor.

16. (Original) A film formation method comprising the steps of:  
forming a first film in a chamber by using a first gas;  
installing a substrate into the chamber after forming the first film; and  
forming a silicon oxide film over a surface of the substrate by using the first film and a second gas.

17. (Original) A film formation method according to claim 16, wherein the first gas comprises a silicide gas and oxygen.

18. (Original) A film formation method according to claim 16, wherein the second gas comprises at least one selected from the group consisting of helium (He), neon (Ne), argon (Ar), krypton (Kr), and xenon (Xe).

19. (Original) A film formation method according to claim 16, wherein the second film is formed at a pressure of 20 Pa or less.

20. (Original) A film formation method according to claim 16, wherein the second film is formed over one selected from the group consisting of a glass substrate, a plastic substrate, and an organic resin film.

21. (Original) A film formation method according to claim 16, wherein the first film is formed by plasma CVD, and the second film is precipitated by sputtering.

22. (Original) A film formation method according to claim 17, wherein the

silicide gas comprises at least one selected from the group consisting of monosilane, disilane, and trisilane.

23. (Original) A film formation method according to claim 16, wherein a semiconductor device is manufactured by using the second film as a protective film of a semiconductor element.

24. (Currently Amended) A film formation method according to claim [[16]] 23, wherein the semiconductor element comprises at least one selected from the group consisting of a thin film transistor, an organic thin film transistor, a thin film diode, a photoelectric conversion element, and a resistor.

25. (Original) A film formation method comprising the steps of:  
forming a first film in a chamber by using a first gas;  
installing a substrate into the chamber after forming the first film; and  
forming a silicon oxynitride film over a surface of the substrate by using the first film and a second gas.

26. (Original) A film formation method according to claim 25, wherein the first gas comprises a silicide gas, oxygen, and nitrogen.

27. (Original) A film formation method according to claim 25, wherein the second gas comprises at least one selected from the group consisting of helium (He), neon (Ne), argon (Ar), krypton (Kr), and xenon (Xe).

28. (Original) A film formation method according to claim 25, wherein the second film is formed at a pressure of 20 Pa or less.

29. (Original) A film formation method according to claim 25, wherein the

second film is formed over one selected from the group consisting of a glass substrate, a plastic substrate, and an organic resin film.

30. (Original) A film formation method according to claim 25, wherein the first film is formed by plasma CVD, and the second film is precipitated by sputtering.

31. (Original) A film formation method according to claim 26, wherein the silicide gas comprises at least one selected from the group consisting of monosilane, disilane, and trisilane.

32. (Original) A film formation method according to claim 25, wherein a semiconductor device is manufactured by using the second film as a protective film of a semiconductor element.

33. (Currently Amended) A film formation method according to claim [[25]] 32, wherein the semiconductor element comprises at least one selected from the group consisting of a thin film transistor, an organic thin film transistor, a thin film diode, a photoelectric conversion element, and a resistor.

34. (New) A method for manufacturing a semiconductor device comprising:  
forming a thin film transistor over a substrate, wherein the thin film transistor comprises an active region and a gate electrode with a gate insulating film interposed therebetween;

forming a first film in a chamber by using a first gas;

installing the substrate into the chamber after forming the first film; and

forming a second film over the thin film transistor by using the first film and a second gas.

35. (New) A method for manufacturing a semiconductor device according

to claim 34, wherein the second film is formed at a pressure of 20 Pa or less.

36. (New) A method for manufacturing a semiconductor device according to claim 34, wherein the substrate comprises at least one selected from the group consisting of a glass substrate, a plastic substrate, and an organic resin film.

37. (New) A method for manufacturing a semiconductor device according to claim 34, wherein the first film is formed by plasma CVD, and the second film is precipitated by sputtering.

38. (New) A method for manufacturing a semiconductor device according to claim 34, further comprising a step of forming an EL layer and an electrode over the second film.

39. (New) A method for manufacturing a semiconductor device comprising:  
forming a thin film transistor over a substrate, wherein the thin film transistor comprises an active region and a gate electrode with a gate insulating film interposed therebetween;

forming a first film in a chamber by using a first gas;  
installing the substrate into the chamber after forming the first film; and  
forming a silicon nitride film over the thin film transistor by using the first film and a second gas.

40. (New) A method for manufacturing a semiconductor device according to claim 39, wherein the first gas comprises a silicide gas and nitrogen.

41. (New) A method for manufacturing a semiconductor device according to claim 40, wherein the silicide gas comprises at least one selected from the group consisting of monosilane, disilane, and trisilane.

42. (New) A method for manufacturing a semiconductor device according to claim 39, wherein the second gas comprises at least one selected from the group consisting of helium (He), neon (Ne), argon (Ar), krypton (Kr), and xenon (Xe).

43. (New) A method for manufacturing a semiconductor device according to claim 39, wherein the second film is formed at a pressure of 20 Pa or less.

44. (New) A method for manufacturing a semiconductor device according to claim 39, wherein the substrate comprises at least one selected from the group consisting of a glass substrate, a plastic substrate, and an organic resin film.

45. (New) A film formation method according to claim 39, wherein the first film is formed by plasma CVD, and the second film is precipitated by sputtering.

46. (New) A method for manufacturing a semiconductor device according to claim 39, further comprising a step of forming an EL layer and an electrode over the second film.

47. (New) A method for manufacturing a semiconductor device comprising:  
forming a thin film transistor over a substrate, wherein the thin film transistor comprises an active region and a gate electrode with a gate insulating film interposed therebetween;

forming a first film in a chamber by using a first gas;

installing the substrate into the chamber after forming the first film; and

forming a silicon oxide film over the thin film transistor by using the first film and a second gas.

48. (New) A method for manufacturing a semiconductor device according

to claim 47, wherein the first gas comprises a silicide gas and nitrogen.

49. (New) A method for manufacturing a semiconductor device according to claim 48, wherein the silicide gas comprises at least one selected from the group consisting of monosilane, disilane, and trisilane.

50. (New) A method for manufacturing a semiconductor device according to claim 47, wherein the second gas comprises at least one selected from the group consisting of helium (He), neon (Ne), argon (Ar), krypton (Kr), and xenon (Xe).

51. (New) A method for manufacturing a semiconductor device according to claim 47, wherein the second film is formed at a pressure of 20 Pa or less.

52. (New) A method for manufacturing a semiconductor device according to claim 47, wherein the substrate comprises at least one selected from the group consisting of a glass substrate, a plastic substrate, and an organic resin film.

53. (New) A film formation method according to claim 47, wherein the first film is formed by plasma CVD, and the second film is precipitated by sputtering.

54. (New) A method for manufacturing a semiconductor device according to claim 47, further comprising a step of forming an EL layer and an electrode over the second film.

55. (New) A method for manufacturing a semiconductor device comprising:  
forming a thin film transistor over a substrate, wherein the thin film transistor comprises an active region and a gate electrode with a gate insulating film interposed therebetween;

forming a first film in a chamber by using a first gas;



installing the substrate into the chamber after forming the first film; and  
forming a silicon oxynitride film over the thin film transistor by using the first film and a second gas.

56. (New) A method for manufacturing a semiconductor device according to claim 55, wherein the first gas comprises a silicide gas and nitrogen.

57. (New) A method for manufacturing a semiconductor device according to claim 56, wherein the silicide gas comprises at least one selected from the group consisting of monosilane, disilane, and trisilane.

58. (New) A method for manufacturing a semiconductor device according to claim 55, wherein the second gas comprises at least one selected from the group consisting of helium (He), neon (Ne), argon (Ar), krypton (Kr), and xenon (Xe).

59. (New) A method for manufacturing a semiconductor device according to claim 55, wherein the second film is formed at a pressure of 20 Pa or less.

60. (New) A method for manufacturing a semiconductor device according to claim 55, wherein the substrate comprises at least one selected from the group consisting of a glass substrate, a plastic substrate, and an organic resin film.

61. (New) A film formation method according to claim 55, wherein the first film is formed by plasma CVD, and the second film is precipitated by sputtering.

62. (New) A method for manufacturing a semiconductor device according to claim 55, further comprising a step of forming an EL layer and an electrode over the second film.